

AG-3046 (XM-3046)

Polymer Thick Film

Description

AG-3046 is a silver filled polymer thick film material designed for a variety of applications in the Printed Electronics space. Exhibiting excellent elastic properties when matched with the appropriate substrate while also providing high conductivity and temperature stability, AG-3046 can be used in a variety of markets including but not limited to wearables, hybrid circuits, medical, and in mold applications.

Key Features

- High elastic properties when matched to appropriate substrate
- Maintains stable conductivity over its useful life
- Highest crease resistance in the PriElex Portfolio
- Highest tested adhesion ranking (ASTM d3359) across a multitude of common substrates
- Excellent cost/performance ratio



This picture does not show the packaging of AG-3046 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms

Typical Properties

Conductivity	<.015 Ω/sq/mil
Viscosity	5.2-5.7 kcps. Brookfield SC4-14 spindle @ SR 20, 25°C
Solids	62% ± 2%
Metal	Ag
Color	Silver
95% Max Particle Size	<25 μm, Hegman

Recommended Processing Guide

Printing Parameters	Monofilament polyester (157 to 230 mesh) or stainless steel (165-325 mesh) is recommended
Drying Temperature	130°C for 5-10 minutes
Process Temperature (TDS)	100-130°C
Film Thickness	8-20 μm DFT
Recommended Thinner	Solvent 30
Paste Compatibility	Compatible with all PriElex products

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Warranty

6 months

Storage

Store at ambient conditions away from direct light. Material should be thoroughly mixed or rolled on a jar roller at a slow speed for 1 hour prior to use

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